# ne<mark>x</mark>peria

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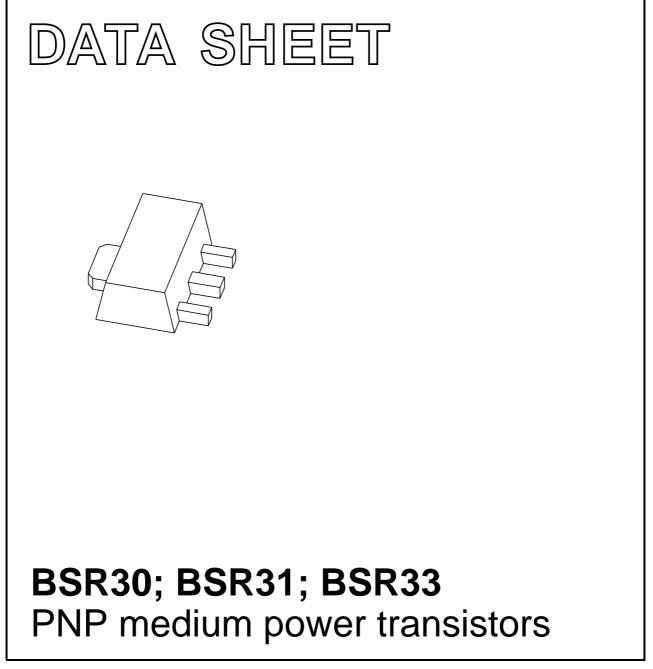
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1999 Apr 26 2004 Dec 13



### FEATURES

- High current (max. 1 A)
- Low voltage (max. 80 V).

### **APPLICATIONS**

- Telephony and general industrial applications
- Thick and thin-film circuits.

### DESCRIPTION

PNP medium power transistor in a SOT89 plastic package. NPN complements: BSR40; BSR41 and BSR43.

### MARKING

TYPE NUMBER	MARKING CODE
BSR30	BR1
BSR31	BR2
BSR33	BR4

# PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base

BSR30; BSR31; BSR33

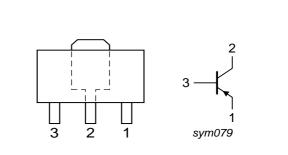


Fig.1 Simplified outline (SOT89) and symbol.

### **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE			
ITPE NUMBER	NAME	DESCRIPTION	VERSION	
BSR30	SC-62 plastic surface mounted package; collector pad for good heat		SOT89	
BSR31		transfer; 3 leads		
BSR33				

### BSR30; BSR31; BSR33

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter			
	BSR30; BSR31		-	-70	V
	BSR33		-	-90	V
V <sub>CEO</sub>	collector-emitter voltage	open base			
	BSR30; BSR31		-	-60	V
	BSR33		-	-80	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	-5	V
I <sub>C</sub>	collector current (DC)		_	-1	A
I <sub>CM</sub>	peak collector current		_	-2	A
I <sub>BM</sub>	peak base current		-	-200	mA
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$ ; note 1	-	1.35	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C

#### Note

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>. For other mounting conditions, see *"Thermal considerations for SOT89 in the General Part of associated Handbook"*.

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	93	K/W
R <sub>th(j-s)</sub>	thermal resistance from junction to soldering point		13	K/W

Note

<sup>1.</sup> Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>. For other mounting conditions, see *"Thermal considerations for SOT89 in the General Part of associated Handbook"*.

# BSR30; BSR31; BSR33

### CHARACTERISTICS

 $T_{amb}$  = 25 °C unless otherwise specified.

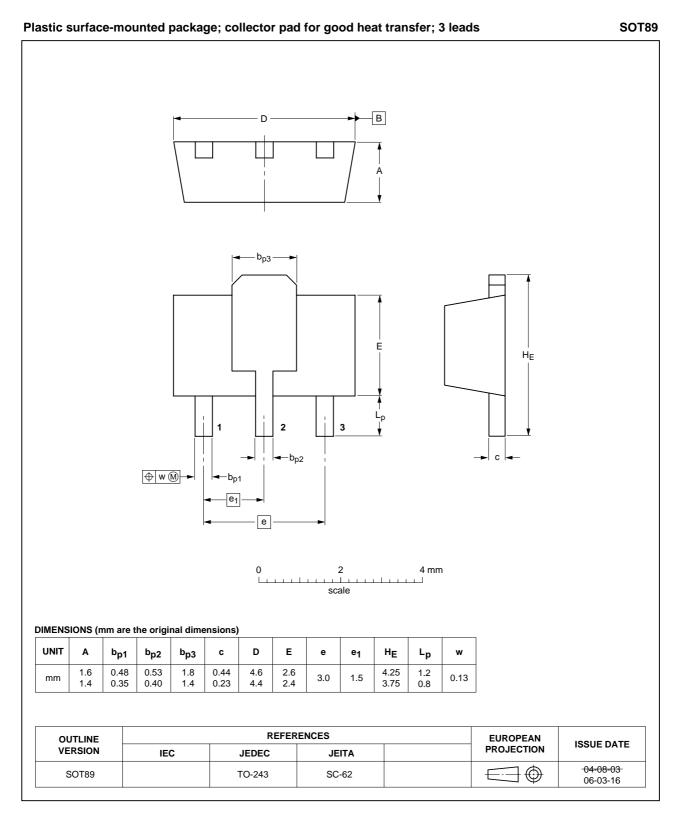
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$I_E = 0 \text{ A}; V_{CB} = -60 \text{ V}$	-	-100	nA
		$I_E = 0 \text{ A}; V_{CB} = -60 \text{ V}; T_j = 150 \text{ °C}$	-	-50	μA
I <sub>EBO</sub>	emitter-base cut-off current	$I_{C} = 0 \text{ A}; V_{EB} = -5 \text{ V}$	-	-100	nA
h <sub>FE</sub>	DC current gain	$I_{C} = -100 \ \mu\text{A}; \ V_{CE} = -5 \ \text{V}; \ \text{note} \ 1$			
	BSR30		10	-	
	BSR31; BSR33		30	-	
	DC current gain	$I_{C} = -100 \text{ mA}; V_{CE} = -5 \text{ V}; \text{ note } 1$			
	BSR30		40	120	
	BSR31; BSR33		100	300	
	DC current gain	$I_{C} = -500 \text{ mA}; V_{CE} = -5 \text{ V}; \text{ note } 1$			
	BSR30		30	-	
	BSR31; BSR33		50	-	
V <sub>CEsat</sub>	collector-emitter saturation	$I_{C} = -150 \text{ mA}; I_{B} = -15 \text{ mA}; \text{ note } 1$	-	-0.25	V
	voltage	$I_{C} = -500 \text{ mA}; I_{B} = -50 \text{ mA}; \text{ note } 1$	-	-0.5	V
V <sub>BEsat</sub>	base-emitter saturation voltage	$I_{C} = -150 \text{ mA}; I_{B} = -15 \text{ mA}; \text{ note } 1$	-	-1	V
		$I_{\rm C} = -500 \text{ mA}; I_{\rm B} = -50 \text{ mA}; \text{ note } 1$	_	-1.2	V
f <sub>T</sub>	transition frequency	$I_{C} = -50 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 100 MHz	100	-	MHz

#### Note

1. Pulse test:  $t_p$  = 300 µs;  $\delta$  < 0.01.

### BSR30; BSR31; BSR33

### PACKAGE OUTLINE



BSR30; BSR31; BSR33

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

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# **NXP Semiconductors**

#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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